

Application Data Sheet

Application Information

Application number::

Filing Date::

Application Type:: Regular

Subject Matter:: Utility

Suggested classification::

Suggested Group Art Unit::

CD-ROM or CD-R??::

Number of CD disks::

Number of copies of CDs::

Sequence Submission::

Computer Readable Form (CRF)?::

Number of copies of CRF::

Title:: METHOD AND APPARATUS FOR RAPID
COOLDOWN OF ANNEALED WAFER

Attorney Docket Number:: 021653-002700US

Request for Early Publication:: No

Request for Non-Publication:: No

Suggested Drawing Figure::

Total Drawing Sheets:: 8

Small Entity?:: No

Latin name::

Variety denomination name::

Petition included?:: No

Petition Type::

Licensed US Govt. Agency::

Contract or Grant Numbers One::

Secrecy Order in Parent Appl.: No

Applicant Information

Applicant Authority Type:: Inventor
Primary Citizenship Country:: Republic of China
Status:: Full Capacity
Given Name:: Chia-Chu
Middle Name::
Family Name:: Kuo
Name Suffix::
City of Residence:: Shanghai
State or Province of Residence::
Country of Residence:: Peoples Republic of China
Street of Mailing Address:: 18 Zhang Jiang Road
Postal Address Line Two:: Pudong New Area
City of Mailing Address:: Shanghai
State or Province of mailing address::
Country of mailing address:: Peoples Republic of China
Postal or Zip Code of mailing address:: 201203

Correspondence Information

Correspondence Customer Number:: 20350

Representative Information

Representative Customer Number:: 20350

Domestic Priority Information

Application:: Continuity Type:: Parent Application:: Parent Filing Date::

Foreign Priority Information

Country:: Application number:: Filing Date::

Peoples Republic of China 200310122958.x

12/30/03

Assignee Information

Assignee Name:: Semiconductor Manufacturing International (Shanghai) Corporation

Street of mailing address:: 18 Zhang Jiang Road, Pudong New Area

City of mailing address:: Shanghai

State or Province of mailing address::

Country of mailing address:: People's Republic of China

Postal or Zip Code of mailing address:: 201203